



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® 1212 SOLDER PROCESS

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
HAST	550	55,000	130°C, 85%RH	0	0.00
Pressure Pot	275	30,360	121°, 15 PSIG	0	0.00
Temp Cycle	1,275	731,250	-65°C-150°C	0	0.00